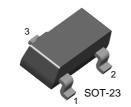


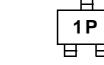
May 2006

KST2222A

NPN Epitaxial Silicon Transistor

General Purpose Transistor





Marking

1. Base 2. Emitter 3. Collector

Absolute Maximum Ratings $T_a = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Value	Units
V _{CBO}	Collector-Base Voltage	75	V
V _{CEO}	Collector-Emitter Voltage	40	V
V _{EBO}	Emitter-Base Voltage	6	V
I _C	Collector Current	600	mA
P _C	Collector Power Dissipation	350	mW
T _{STG}	Storage Temperature Range	-55 ~ 150	°C

Electrical Characteristics T_a =25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units
BV _{CBO}	Collector-Base Breakdown Voltage	$I_C = 10\mu A, I_E = 0$	75		V
BV _{CEO}	Collector-Emitter Breakdown Voltage	$I_C = 10 \text{mA}, I_B = 0$	40		V
BV _{EBO}	Emitter-Base Breakdown Voltage	$I_E = 10\mu A, I_C = 0$	6		V
I _{CBO}	Collector Cut-off Current	V _{CB} = 60V, I _E = 0		0.01	μΑ
h _{FE}	DC Current Gain *	$\begin{split} &V_{CE} = 10V, \ I_{C} = 0.1 \text{mA} \\ &V_{CE} = 10V, \ I_{C} = 1 \text{mA} \\ &V_{CE} = 10V, \ I_{C} = 10 \text{mA} \\ &V_{CE} = 10V, \ I_{C} = 150 \text{mA} \\ &V_{CE} = 10V, \ I_{C} = 500 \text{mA} \end{split}$	35 50 75 100 40	300	
V _{CE} (sat)	Collector-Emitter Saturation Voltage *	I _C = 150mA, I _B = 15mA I _C = 500mA, I _B = 50mA		0.3 1.0	V V
V _{BE} (sat)	Base-Emitter Saturation Voltage *	I _C = 150mA, I _B = 15mA I _C = 500mA, I _B = 50mA	0.6	1.2 2.0	V V
f _T	Current Gain Bandwidth Product	$I_C = 20$ mA, $V_{CE} = 20$ V, $f = 100$ MHz	300		MHz
C _{ob}	Output Capacitance	V _{CB} = 10V, I _E = 0, f = 1MHz		8	pF
NF	Noise Figure	I_C = 100μA, V_{CE} = 10V R _S = 1KΩ, f = 1MHz		4	dB
t _{ON}	Turn On Time	$V_{CC} = 30V, I_{C} = 150mA$ $V_{BE} = 0.5V, I_{B1} = 15mA$		35	ns
t _{OFF}	Turn Off Time	V _{CC} = 30V, I _C = 150mA, I _{B1} = I _{B2} = 15mA		285	ns

^{*} Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%

Typical Performance Characteristics

Figure 1. DC Current Gain

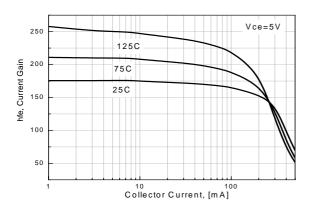


Figure 2. Collector-Emitter Saturation Voltage

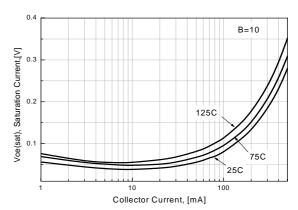


Figure 3. Base-Emitter Saturation Voltage

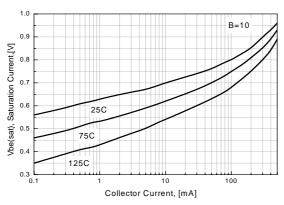


Figure 4. Collector - Base Leakage Current

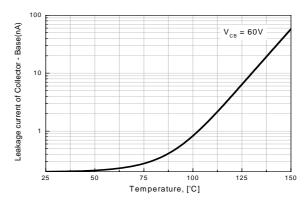


Figure 5. Output Capacitance

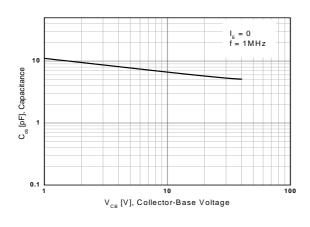
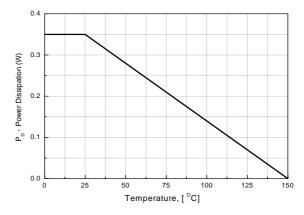


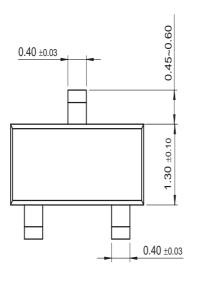
Figure 6. Power Dissipation vs Ambient Temperature

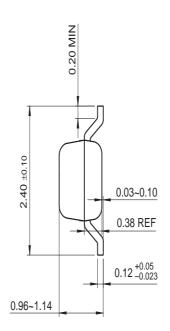


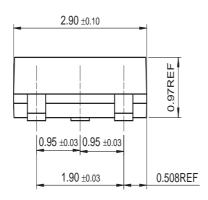
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Mechanical Dimensions

SOT-23







Dimensions in Millimeters

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FACT Quiet Series™		OPTOPLANAR™	SILENT SWITCHER®	UniFET™
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